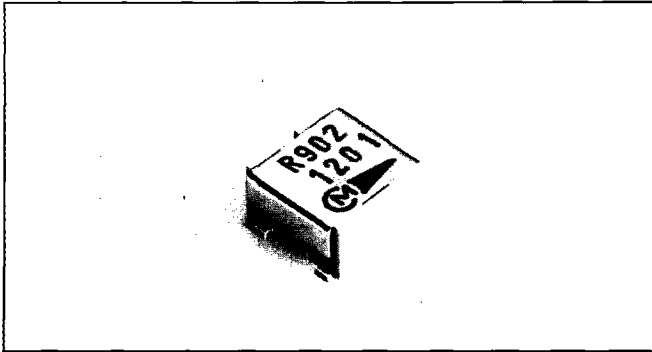


MICROWAVE ISOLATOR-SURFACE MOUNT

CEO60 Series



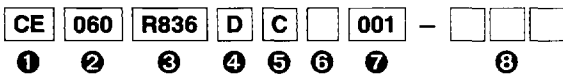
FEATURES

- Surface mount
- Reflow soldering capability
- Miniature size (6.8 × 6.9 × 4mm)
- Light weight (0.8g)
- High reliability

APPLICATIONS

- Hand Held Telephone
- Cordless Telephone
- Interstage matching in microwave circuits

PART NUMBERING



- ① Series Name
- ② Model Number
- ③ Center Frequency (express in GHz, R : indicate decimal point)
- ④ Band Width
- ⑤ Rated Power
- ⑥ Signal Direction (Specify A or B in Fig-1)
- ⑦ Standard type has no number. (Additional numbers for special specification)
- ⑧ Packaging Type TA1 : 178mm Dia. reel taping (250 pcs/reel)
TA2 : 330mm Dia. reel taping (1000 pcs/reel)
nothing : bulk

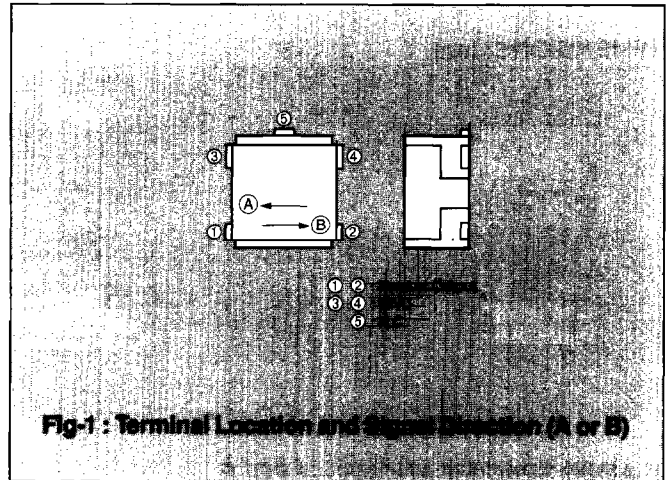


Fig-1 : Terminal Location and Signal Direction (A or B)

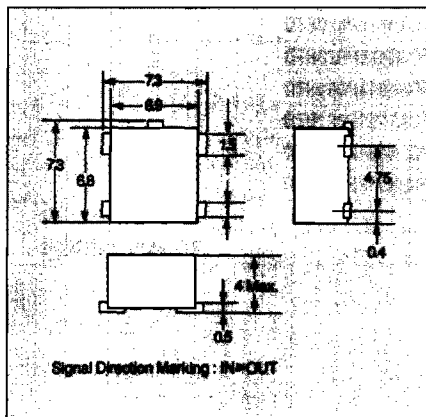
SPECIFICATIONS

Part Number	Frequency Range (MHz)*	Insertion Loss (dB)	Isolation (dB)	VSWR	Rated Power (W)	Reflected Power (W)**
CE060R836DC□	824 to 849	1.0 max. (-35 to +85°C)	12 min. (-35 to +85°C)	1.6 max. (-35 to +85°C)	2.5	0.5
CE060R888DC□	872 to 905					
CE060R902DC□	890 to 915					
CE060R911DC□	898 to 925					
CE060R933CC□	925 to 942					

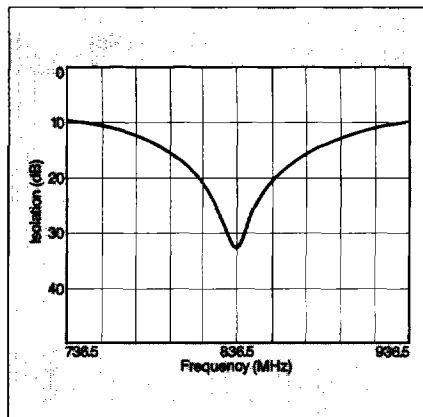
*Note : Other frequency range is also available on request.

**Note : Case surface temperature should be less than 100°C.

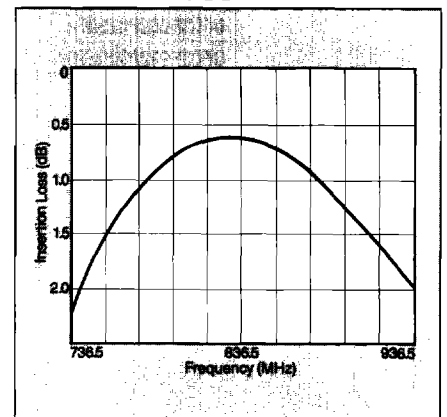
DIMENSIONS: mm



ISOLATION



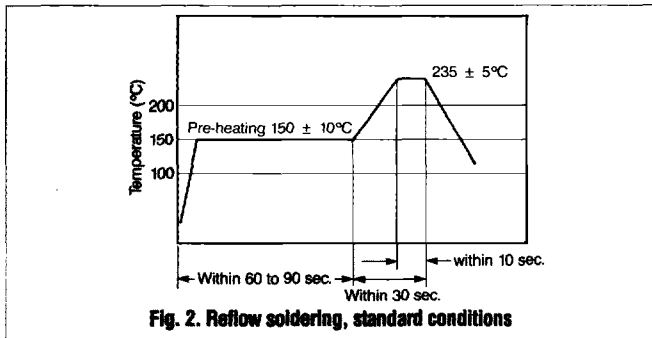
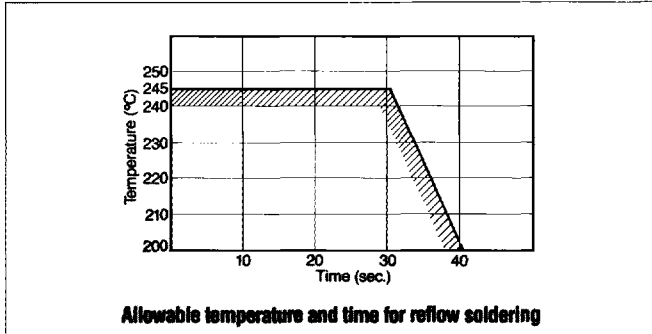
INSERTION LOSS



SOLDERING

1. Reflow Soldering

Soldering must be carried out without exceeding the approved soldering temperature and time shown within the shaded area in Fig. 1. When soldering is repeated, the allowed time is the accumulated time. The standard soldering conditions are shown in Fig. 2.



2. Soldering with soldering iron

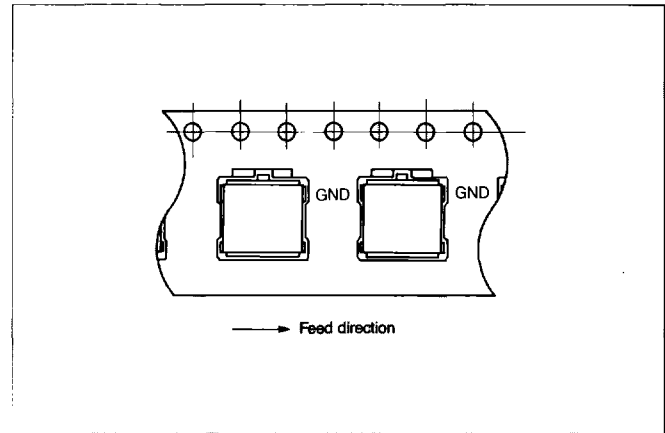
Soldering with soldering iron should be carried out according to the following conditions.

- ① Pre-heating
Temperature: 150°C.
Time: 60 to 120sec.
- ② Temperature (at the tip of the soldering iron): less than 280°C.
Time: less than 10sec.

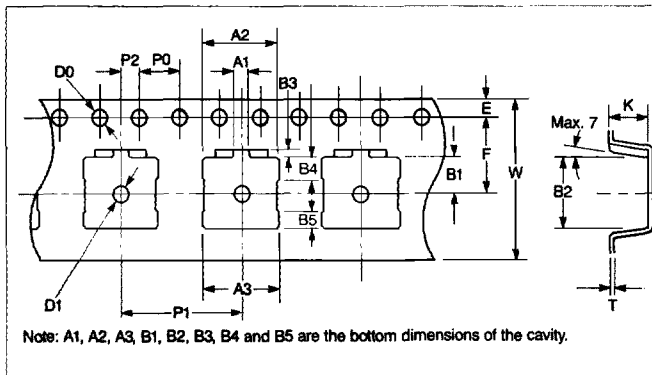
MOUNTING

When mounting the CE060 series isolator with a component placement machine, a non-magnetic tool should be used since there is some magnetic leakage from the isolator.

TERMINAL DIRECTION

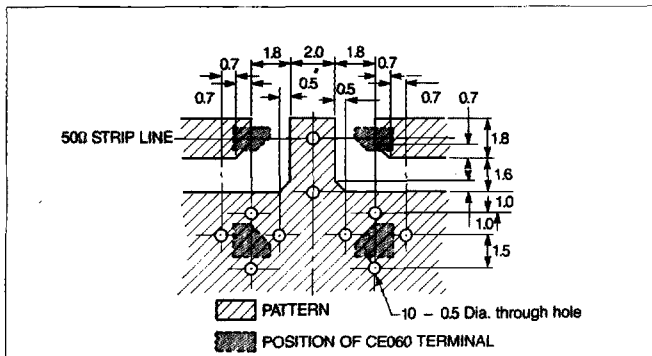


TAPE DIMENSIONS : mm

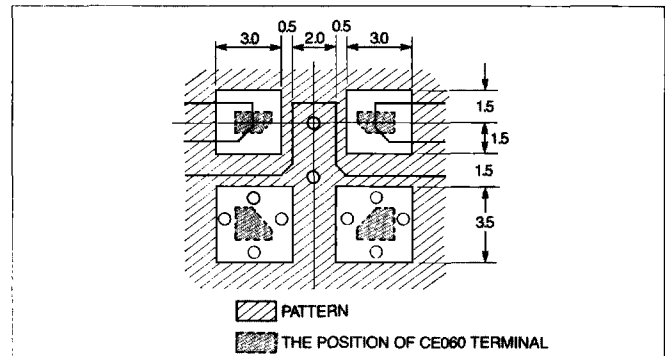


A1	A2	A3	B1	B2	B3
1.6±0.1	7.2±0.1	7.7±0.1	3.6±0.05	7.2±0.1	0.7±0.1
B4	B5	W	D0	D1	E
2.3±0.1	1.8±0.1	16±0.2	1.55±0.05 Dia.	1.5Min.	1.75±0.1
F	K	P0	P1	P2	T
7.5±0.1	4±0.1	4±0.1	12±0.1	2±0.1	0.3±0.05

PAD DIMENSIONS : mm COPPER ELECTRODE PATTERN



PAD DIMENSIONS : mm SOLDER RESIST PATTERN



Substrate thickness: t = 1.0mm
Dielectric Constant $\epsilon_r = 4.7$